This application note describes the schematic and layout requirements for using the BGA3012 as a CATV drop amplifier.
Contact information

For more information, please visit: http://www.nxp.com

For sales office addresses, please send an email to: salesaddresses@nxp.com
1. Introduction

The BGA3012 customer evaluation board enables the user to evaluate the performance of the wideband CATV MMIC amplifier BGA3012.

The BGA3012 performance information is available in the BGA3012 datasheet.

This application note describes the evaluation board schematic and layout requirements for using the BGA3012 as a CATV drop amplifier between 40 MHz and 1003 MHz. The BGA3012 is fabricated in the BiCMOS process and packaged in a lead-free 3-pin SOT89 package. The BGA3012 is surface-mounted on an evaluation board with element matching and DC decoupling circuitry. The amplifier MMIC comprises a two stage amplifier with internal bias network and operates over a frequency range of 5 MHz to 1003 MHz with a supply voltage between 5 V and 8 V.

2. System features

- 12 dB gain
- Internally biased
- Flat gain between 40 MHz and 1003 MHz
- Noise figure of 3.2 dB
- High linearity with an IP3 of 40 dBm and IP2 of 60 dBm
- 75 Ω input and output impedance
- Unconditionally stable
- Excellent input and output return loss

3. Customer evaluation kit contents

The evaluation kit contains the following items:

- ESD safe casing
- BGA3012 evaluation board
- BGA3012 SOT89 samples
4. Application Information

For evaluation purposes an evaluation board is available. The evaluation circuit can be seen in figure 1 and the corresponding PCB is shown in figure 2. Table 1 shows the bill of materials.

4.1 Evaluation board circuit

The power supply is applied on the center pin of connector J3 and is applied to the MMIC via chokes L4 and L2 which provides RF blocking to the supply line. Choke L4 is put in series with choke L2 to improve the performance at frequencies below 100 MHz. Capacitors C4 and C5 are supply decoupling capacitors.

At the F-connector J1 the RF input signal is applied where capacitor C1 provides DC-blocking, followed by L1 for input matching (Z = 75 Ω). Resistors R1 and R2 are used as feedback resistors to set the gain and slope. Two resistors are used to lower the influence of the parasitic capacitance from the circuit board. Capacitor C2 provides DC-blocking between the input and output of the MMIC. Inductor L3 provides the output matching (Z = 75 Ω) at the MMICs output followed by C3 for DC-blocking before the RF signal is available at F-connector J2.
### 4.2 Evaluation board layout

![BGA3012 Evaluation Board Layout](image)

**Fig 2. BGA3012 evaluation board layout**

For optimum distortion performance it is important to have enough ground vias underneath and around the MMICs ground pins. This lowers the inductance to the ground plane. The evaluation board is made with two layer FR4 material.

- PCB material = FR4
- PCB thickness = 1.5 mm
- PCB size = 40 mm x 40 mm
- $\varepsilon_r$ = 4.6
- Copper thickness = 35 µm
4.3 Bill of materials

Table 1. Evaluation board BOM

<table>
<thead>
<tr>
<th>Circuit Reference</th>
<th>Description</th>
<th>Qty</th>
<th>Mfr</th>
<th>Manufacturer number</th>
<th>Supplier</th>
<th>Supplier part number</th>
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<tr>
<td>U1</td>
<td>BGA3012</td>
<td>1</td>
<td>NXP</td>
<td>BGA3012</td>
<td>NXP</td>
<td>BGA3012</td>
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<td>C1, C2, C3, C4</td>
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<td>GRM155R71E103KA01D</td>
<td>Digikey</td>
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<tr>
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<td>L2</td>
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<td>R1</td>
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<td>J1, J2</td>
<td>75 Ω F-connector</td>
<td>2</td>
<td>Bomar</td>
<td>861V509ER6</td>
<td>Mouser</td>
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<td>J3</td>
<td>Header 3</td>
<td>1</td>
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<td>WM8109-ND</td>
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</table>
5. Measurement results at $Vcc = 8$ V

5.1 S-Parameters

Fig 3. Input matching ($S_{11}$); $Vcc = 8$ V

Fig 4. Output matching ($S_{22}$); $Vcc = 8$ V
Fig 5. Gain (S21); Vcc = 8 V

(1) Tamb = -40 °C  
(2) Tamb = +25 °C  
(3) Tamb = +85 °C

Fig 6. K-factor; Vcc = 8 V

(1) Tamb = -40 °C  
(2) Tamb = +25 °C  
(3) Tamb = +85 °C
5.2 Distortion

![Graph showing CTB and CSO distortion](image)

(1) Tamb = +25 °C
132 channels NTSC, Vo = 30 dBmV

**Fig 7.** Composite triple beat (CTB); Vcc = 8 V

![Graph showing CSO distortion](image)

(1) Tamb = +25 °C
132 channels NTSC, Vo = 30 dBmV

**Fig 8.** Composite second order (CSO); Vcc = 8 V
5.3 Noise figure

(1) Tamb = +25 °C
(2) Tamb = +85 °C
(3) Tamb = -30 °C

Fig 9. Cross modulation (XMOD); Vcc = 8 V

Fig 10. Noise figure (NF); Vcc = 8 V

132 channels NTSC, Vo = 30 dBmV
5.4 Output P1dB

Fig 11. Output P1dB; Vcc = 8 V

5.5 Output IP2

Fig 12. Output IP2; Vcc = 8 V
5.6 Output IP3

![Output IP3 Graph]

(1) Tamb = -40 °C  
(2) Tamb = +25 °C  
(3) Tamb = +85 °C  

\[ f_2 = f_1 \pm 6 \text{ MHz} \text{, input power} = -20 \text{ dBm} \]

**Fig 13. Output IP3; Vcc = 8 V**
6. Measurement results at Vcc = 5 V

6.1 S-Parameters

**Fig 14.** Input matching (S11); Vcc = 5 V

**Fig 15.** Output matching (S22); Vcc = 5 V
Fig 16. Gain (S21); Vcc = 5 V

Fig 17. K-factor; Vcc = 5 V
6.2 Distortion

![Composite triple beat (CTB) graph](image1)

(1) \(T_{amb} = +25 \, ^\circ C\)
132 channels NTSC, \(V_o = 30 \, \text{dBmV}\)

**Fig 18.** Composite triple beat (CTB); \(V_{cc} = 5 \, \text{V}\)

![Composite second order (CSO) graph](image2)

(1) \(T_{amb} = +25 \, ^\circ C\)
132 channels NTSC, \(V_o = 30 \, \text{dBmV}\)

**Fig 19.** Composite second order (CSO); \(V_{cc} = 5 \, \text{V}\)
6.3 Noise Figure

Fig 21. Noise figure (NF); Vcc = 5 V
6.4 Output P1dB

(1) Tamb = -40 °C  
(2) Tamb = +25 °C  
(3) Tamb = +85 °C

Fig 22. Output P1dB; Vcc = 5 V

6.5 Output IP2

(1) Tamb = -40 °C  
(2) Tamb = +25 °C  
(3) Tamb = +85 °C

\( f_2 = f_1 \pm 6 \text{ MHz} \), input power = -20 dBm

Fig 23. Output IP2; Vcc = 5 V

6.6 Output IP3
Fig 24. Output IP3; Vcc = 5 V

(1) Tamb = -40 °C
(2) Tamb = +25 °C
(3) Tamb = +85 °C

\[ f_2 = f_1 \pm 6 \text{ MHz}, \text{ input power} = -20 \text{ dBm} \]
7. Abbreviations

Table 2. Abbreviations

<table>
<thead>
<tr>
<th>Acronym</th>
<th>Description</th>
</tr>
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<tbody>
<tr>
<td>AC</td>
<td>Alternating Current</td>
</tr>
<tr>
<td>CATV</td>
<td>Community Antenna TeleVision</td>
</tr>
<tr>
<td>DC</td>
<td>Direct Current</td>
</tr>
<tr>
<td>ESD</td>
<td>Electro Static Discharge</td>
</tr>
<tr>
<td>MMIC</td>
<td>Monolithic Microwave Integrated Circuit</td>
</tr>
<tr>
<td>NTSC</td>
<td>National Television Standards Committee</td>
</tr>
<tr>
<td>PCB</td>
<td>Printed Circuit Board</td>
</tr>
<tr>
<td>RF</td>
<td>Radio Frequency</td>
</tr>
<tr>
<td>SMD</td>
<td>Surface Mounted Device</td>
</tr>
</tbody>
</table>
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